

EAST Search History

S97	3	(257/E21.511).cccls. and flexible with substrate and chip and internal with (electrode or connect\$4) and external with (electrode or connect\$4) and solder near resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 00:26
S98	0	(257/E21.069).cccls. and flexible with substrate and chip and internal with (electrode or connect\$4) and external with (electrode or connect\$4) and solder near resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 00:26
S99	9	(257/E21.\$).cccls. and flexible with substrate and chip and internal with (electrode or connect\$4) and external with (electrode or connect\$4) and solder near resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 00:26
S10 0	27	(257/E23.\$).cccls. and flexible with substrate and chip and internal with (electrode or connect\$4) and external with (electrode or connect\$4) and solder near resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/14 00:27
S10 1	475	(257/616).cccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 16:06
S10 2	361374	("257"/\$).cccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 13:53
S10 3	30335	flexible near substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 13:56
S10 4	1596	(passivat\$4 or protect\$4) with solder adj resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 13:57